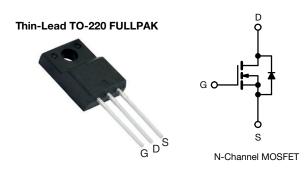
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	850)
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.25
Q _g max. (nC)	62	
Q _{gs} (nC)	8	
Q _{gd} (nC)	18	
Configuration	Sing	le

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High intensity discharge (HID)
- Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SiHA17N80AE-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V _{DS}	800	
Gate-source voltage		V_{GS}	± 30	V	
Continuous drain current (T _{.I} = 150 °C) e)/ -+ 10.\/	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$,	7	
Continuous drain current (1j = 150 °C) °	V _{GS} at 10 V	T _C = 100 °C	I _D	4	Α
Pulsed drain current ^a			I _{DM}	32	
Linear derating factor				0.27	W/°C
Single pulse avalanche energy ^b			E _{AS}	127	mJ
Maximum power dissipation			P _D	34	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	T _J = 125 °C		dV/dt	100	V/ns
Reverse diode dV/dt ^d			av/at	17	V/IIS
Soldering recommendations (peak temperature) ^c	For	10 s		260	°C
Mounting torque	M3 s	screw		0.6	Nm

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature b. $V_{DD}=140~V$, starting $T_J=25~^{\circ}C$, L=28.2~mH, $R_g=25~\Omega$, $I_{AS}=3.0~A$
- 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C
- Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	3.7	C/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.8	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	٧
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
	I _{DSS}	V _{DS} =	V _{DS} = 800 V, V _{GS} = 0 V		-	1	
Zero gate voltage drain current		V _{DS} = 640 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8.5 A	ı	0.25	0.29	Ω
Forward transconductance	9 _{fs}	V _{DS} = 10 V, I _D = 8.5 A		-	7.1	-	S
Dynamic		•					
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	1260	-	pF
Output capacitance	C _{oss}			-	56	-	
Reverse transfer capacitance	C _{rss}			-	5	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	40	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	245	-	
Total gate charge	Qg		-	41	62		
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 8.5 \text{ A}, V_{DS} = 640 \text{ V}$	-	8	-	nC
Gate-drain charge	Q _{gd}	7		-	18	-	
Turn-on delay time	t _{d(on)}	$V_{DD} = 640 \text{ V}, I_D = 8.5 \text{ A}, V_{GS} = 10 \text{ V}, R_a = 9.1 \Omega$		-	21	42	ns
Rise time	t _r			-	23	46	
Turn-off delay time	t _{d(off)}			-	45	90	
Fall time	t _f	7	g		31	62	
Gate input resistance	R_g	f = 1 MHz, open drain		0.2	0.5	1.1	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	
Pulsed diode forward current	I _{SM}			-	-	32	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 8.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 8.5 A, dl/dt = 100 A/ μ s, V _R = 25 V		-	314	628	ns
Reverse recovery charge	Q _{rr}			-	4	8	μC
Reverse recovery current	I _{RRM}			_	21	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

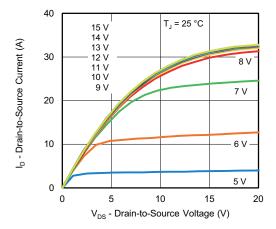


Fig. 1 - Typical Output Characteristics

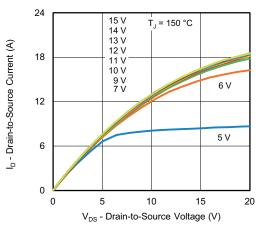


Fig. 2 - Typical Output Characteristics

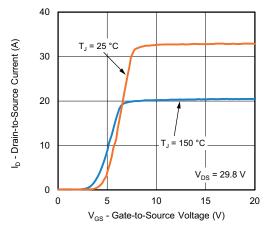


Fig. 3 - Typical Transfer Characteristics

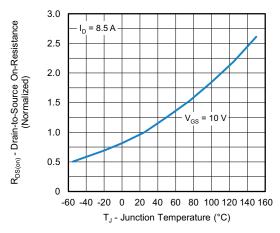


Fig. 4 - Normalized On-Resistance vs. Temperature

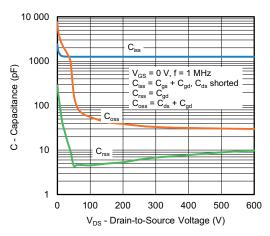


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

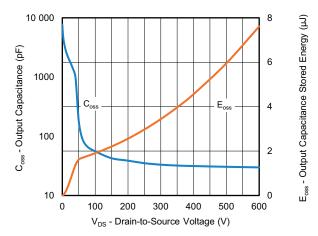


Fig. 6 - Coss and Eoss vs. VDS



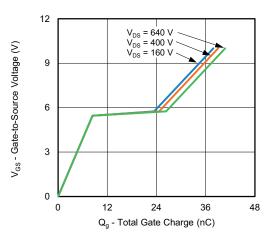


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

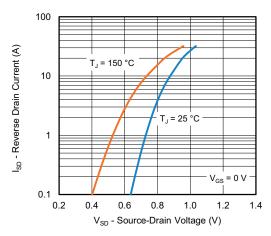


Fig. 8 - Typical Source-Drain Diode Forward Voltage

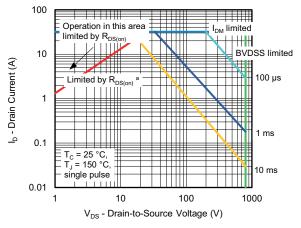


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

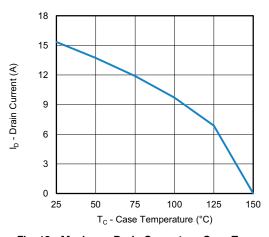


Fig. 10 - Maximum Drain Current vs. Case Temperature

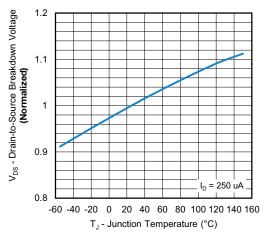


Fig. 11 - Temperature vs. Drain-to-Source Voltage



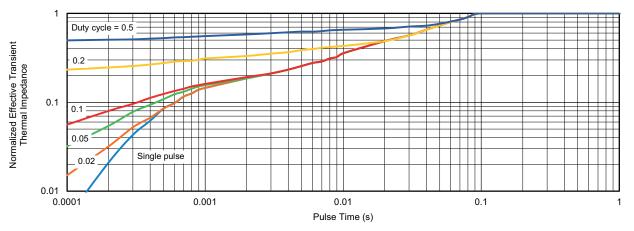


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

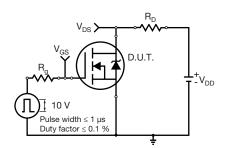


Fig. 13 - Switching Time Test Circuit

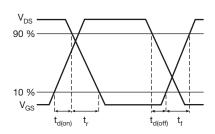


Fig. 14 - Switching Time Waveforms

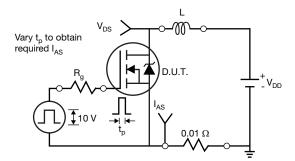


Fig. 15 - Unclamped Inductive Test Circuit

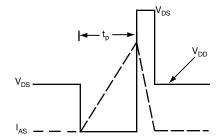


Fig. 16 - Unclamped Inductive Waveforms

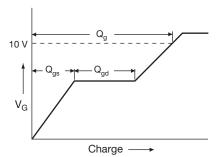


Fig. 17 - Basic Gate Charge Waveform

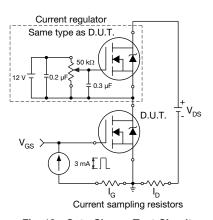
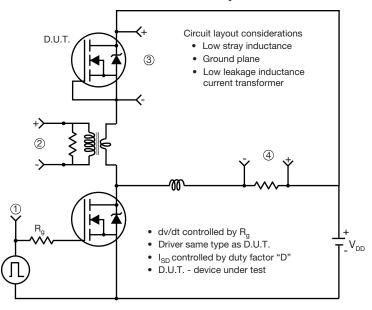


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



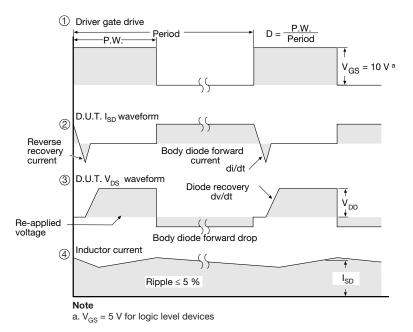


Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





SYMBOL	DIMENSIONS				
	MILLIN	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.40	2.80	0.094	0.110	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.30	3.70	0.130	0.146	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	1.00	2.80	0.039	0.110	
ØP	3.00	3.40	0.118	0.134	

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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